

IMPROVED SURFACE MOUNT PACKAGE

ABSTRACT OF THE DISCLOSURE

Space-efficient packaging of microelectronic devices permits greater functionality per unit PC board surface area. In certain embodiments, packages having leads of a reverse gull wing shape reduce peripheral footprint area occupied by the leads, thereby permitting maximum space in the package footprint to be allocated to the package body and to the enclosed die. Embodiments of packages in accordance with the present invention may also reduce the package vertical profile by featuring recesses for receiving lead feet ends, thereby reducing clearance between the package bottom and the PC board. Providing a linear lead foot underlying the package and slightly inclined relative to the PC board further reduces vertical package profile by eliminating additional clearance associated with radii of curvature of J-shaped leads.

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